

N-Channel Enhancement Mode Power MOSFET

Description

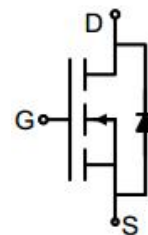
The GT1K2N10I uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.

General Features

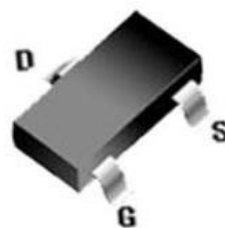
- V_{DS} 100V
- I_D (at $V_{GS} = 10V$) 3.3A
- $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 110m Ω
- $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) < 135m Ω
- 100% Avalanche Tested
- RoHS Compliant

Application

- Power switch
- DC/DC converters



Schematic diagram



SOT-23

Ordering Information

Device	Package	Marking	Packaging
GT1K2N10I	SOT-23	GT1K2N10	3000pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Continuous Drain Current	I_D	3.3	A
Pulsed Drain Current (note1)	I_{DM}	13.2	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	P_D	1.6	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient, $t \leq 10s$	R_{thJA}	78	$^\circ\text{C/W}$

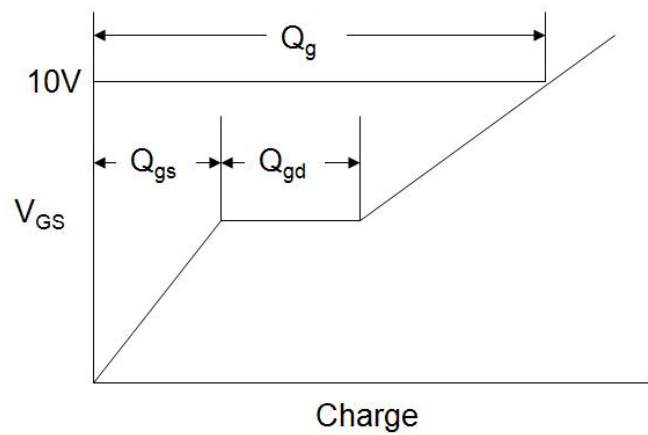
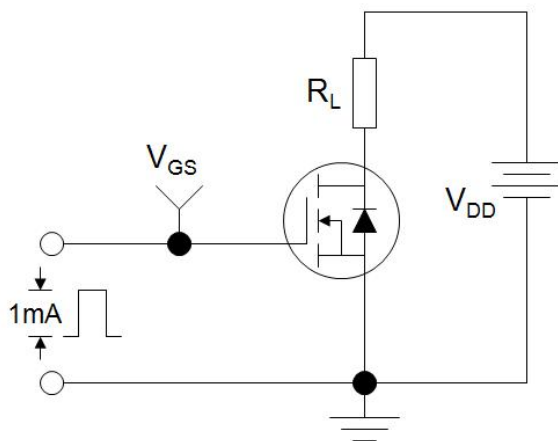
Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100	--	--	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V	--	--	1	μA
Gate-Source Leakage	I _{GSS}	V _{GS} = ±20V	--	--	±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.7	2.2	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 3A	--	91	110	mΩ
		V _{GS} = 4.5V, I _D = 2A	--	113	135	
Forward Transconductance	g _{FS}	V _{GS} = 5V, I _D = 3A	--	3	--	S
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 50V, f = 1.0MHz	--	145	--	pF
Output Capacitance	C _{oss}		--	40	--	
Reverse Transfer Capacitance	C _{rss}		--	3	--	
Total Gate Charge	Q _g	V _{DD} = 50V, I _D = 3A, V _{GS} = 10V	--	4.2	--	nC
Gate-Source Charge	Q _{gs}		--	0.6	--	
Gate-Drain Charge	Q _{gd}		--	1.1	--	
Turn-on Delay Time	t _{d(on)}	V _{DD} = 50V, I _D = 3A, R _G = 2Ω	--	15	--	ns
Turn-on Rise Time	t _r		--	4	--	
Turn-off Delay Time	t _{d(off)}		--	21	--	
Turn-off Fall Time	t _f		--	3	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I _S	T _C = 25°C	--	--	3.3	A
Body Diode Voltage	V _{SD}	T _J = 25°C, I _{SD} = 3A, V _{GS} = 0V	--	--	1.2	V
Reverse Recovery Charge	Q _{rr}	I _F = 3A, V _{GS} = 0V di/dt=100A/us	--	40	--	nC
Reverse Recovery Time	T _{rr}		--	33	--	ns

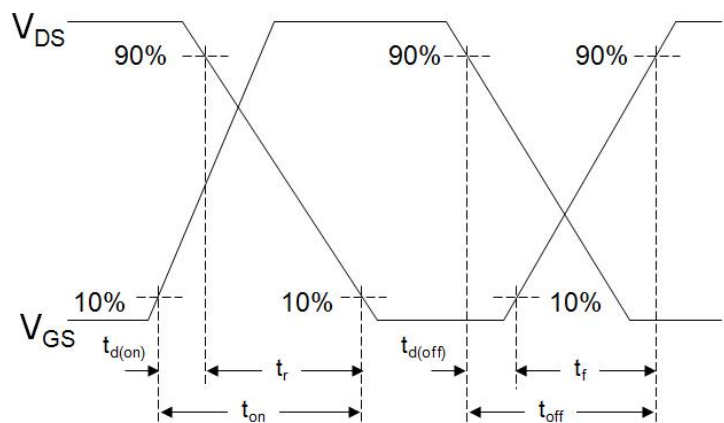
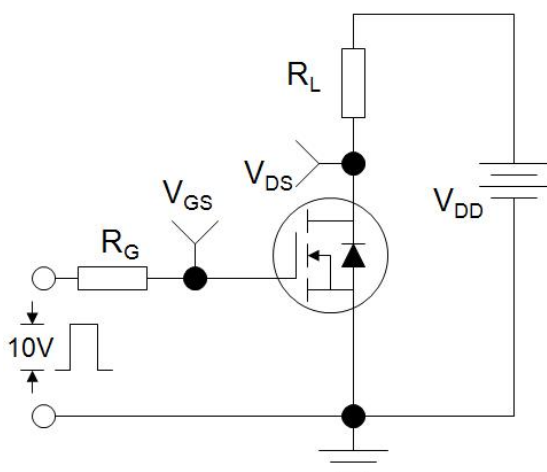
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical R_G

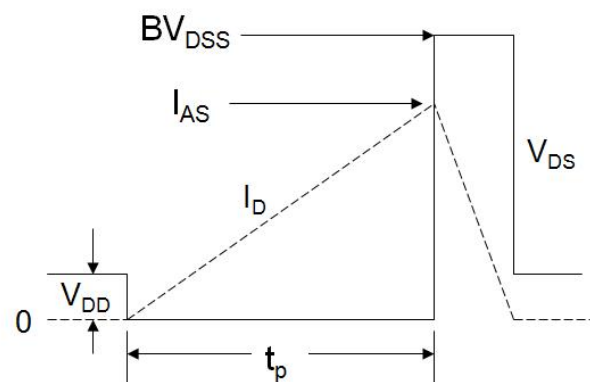
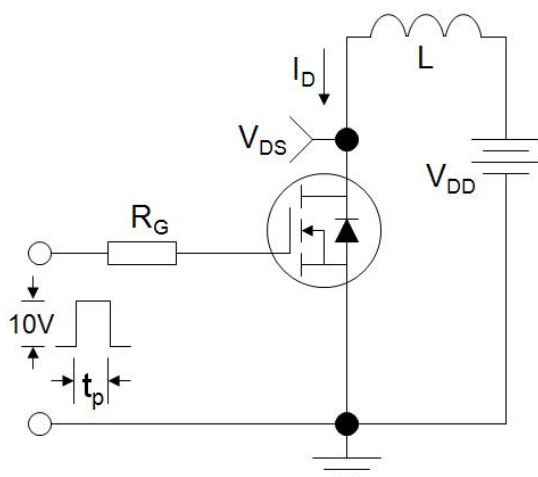
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

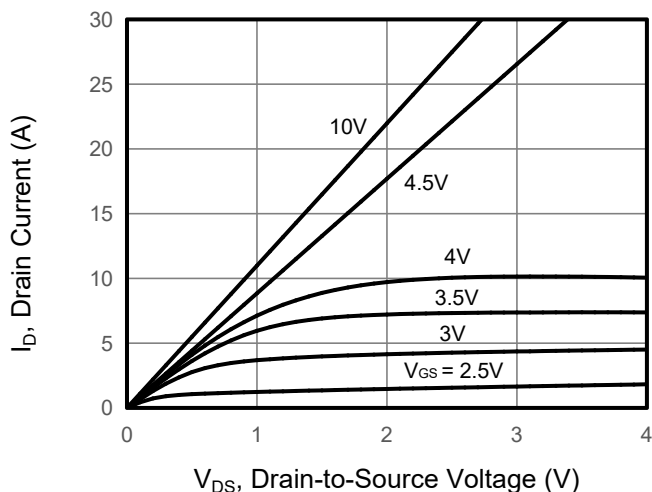


Figure 2. Transfer Characteristics

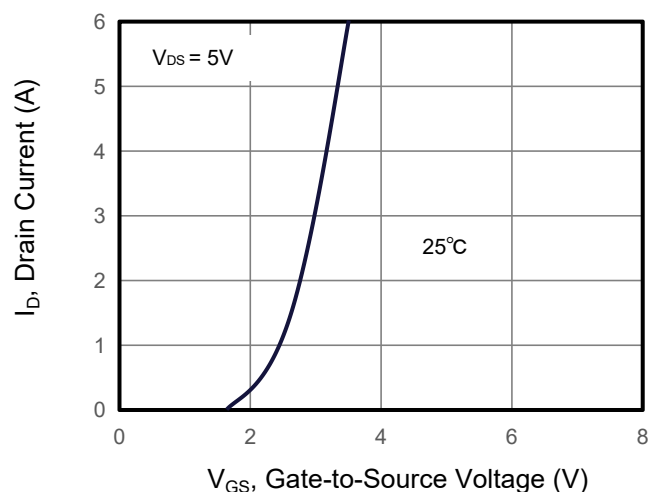


Figure 3. Drain Source On Resistance

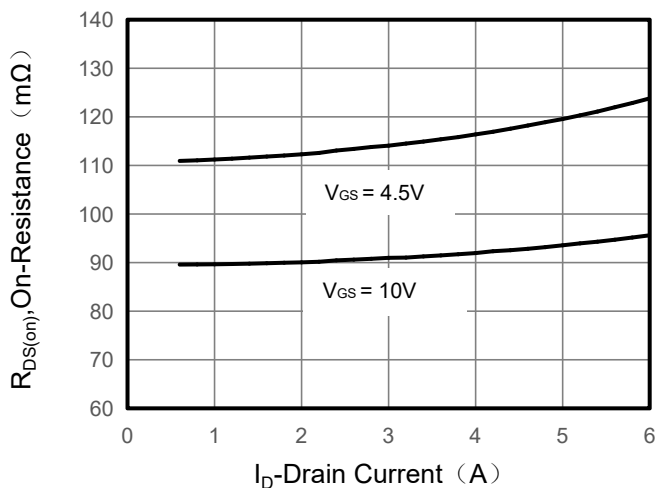


Figure 4. Gate Charge

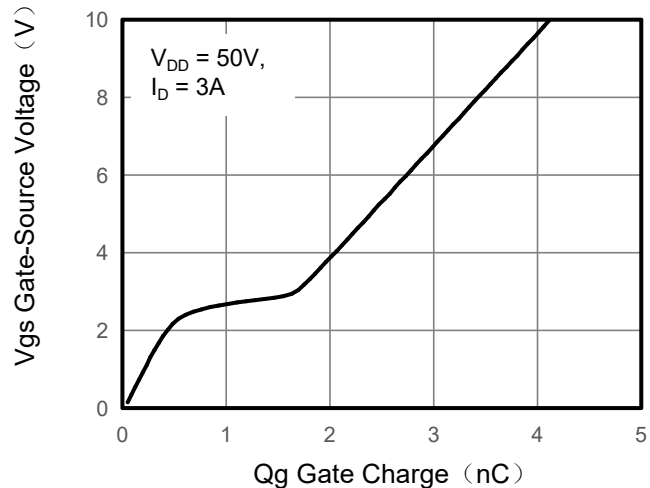


Figure 5. Capacitance

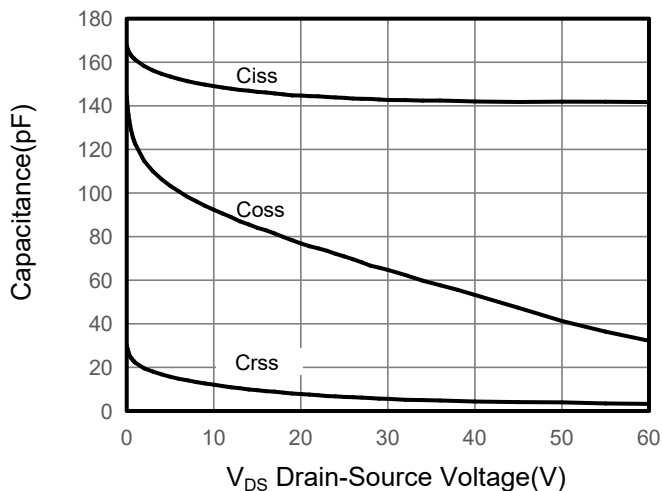
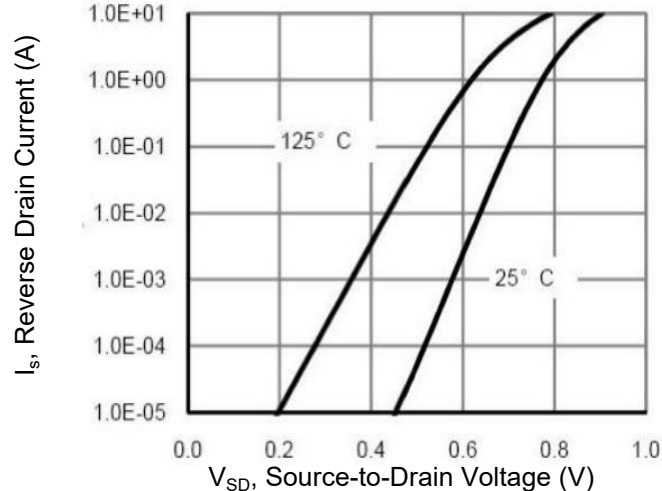


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

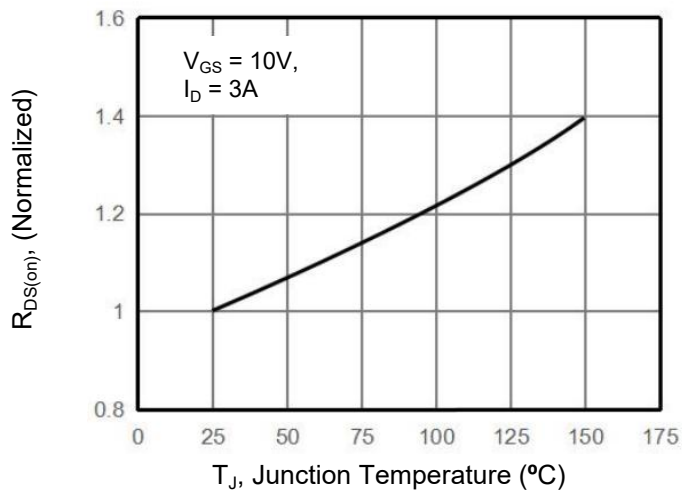


Figure 8. Safe Operation Area

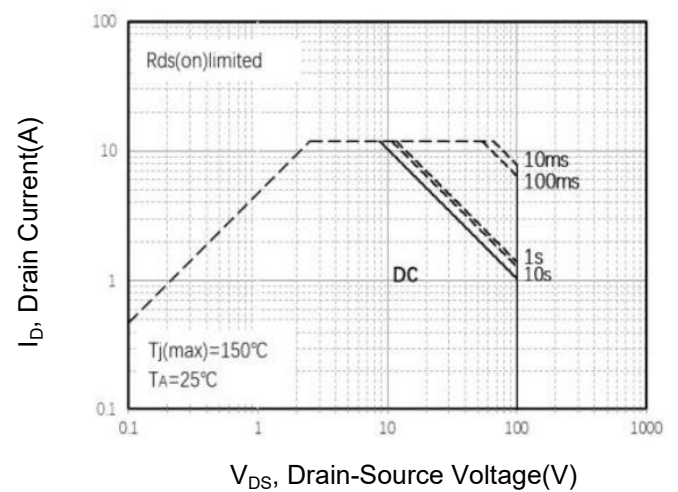
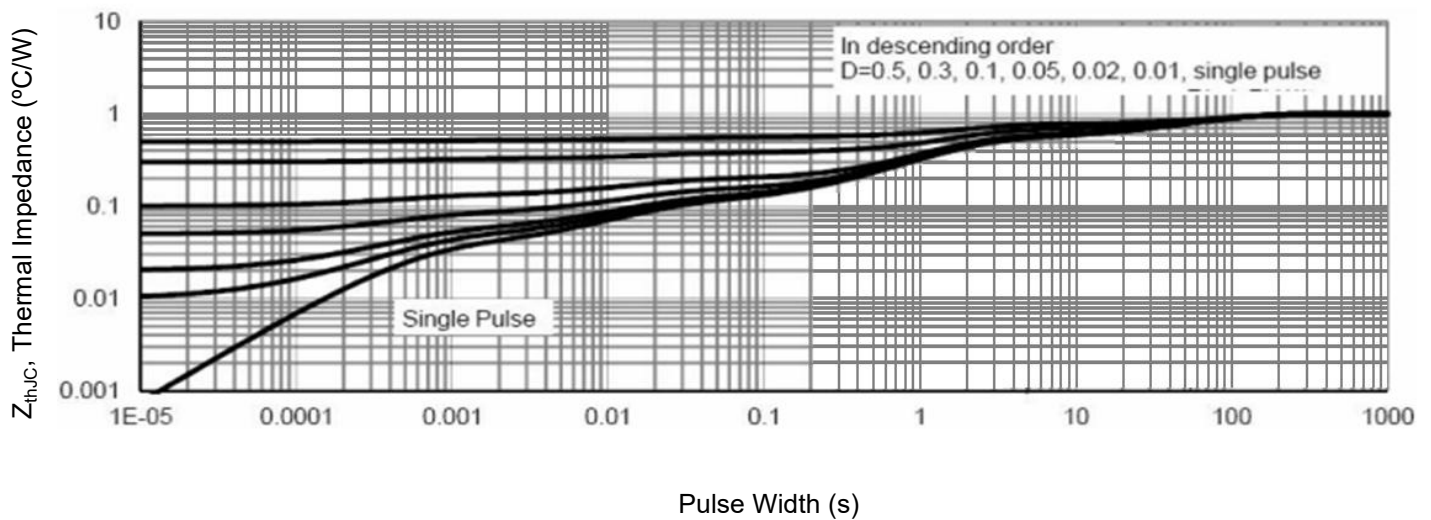
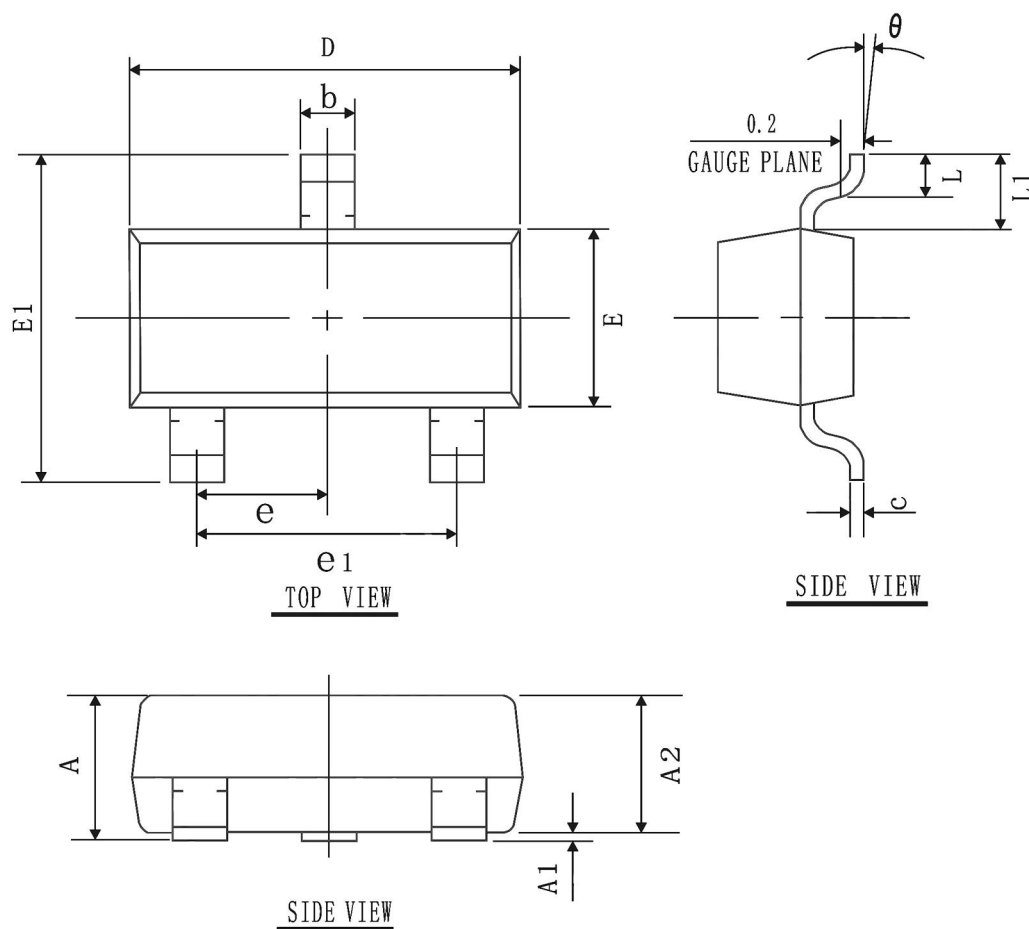


Figure 9. Normalized Maximum Transient Thermal Impedance



SOT-23 Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.90	1.05	1.20
A1	0.00	0.05	0.10
A2	0.90	1.00	1.10
b	0.30	0.40	0.50
c	0.08	0.10	0.15
D	2.80	2.90	3.00
E	1.20	1.30	1.40
E1	2.30	2.40	2.50
L	0.30	0.40	0.50
θ	0°	5°	10°
L1	0.55 REF		
e	0.95 BSC		
e1	1.90 REF		